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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	55
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	3K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 5.5V
Data Converters	A/D 12x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f212a8sdfa-v2

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1.2 Product List

Table 1.5 lists Product List for R8C/2A Group, Figure 1.1 shows a Part Number, Memory Size, and Package of R8C/2A Group, Table 1.6 lists Product List for R8C/2B Group, and Figure 1.2 shows a Part Number, Memory Size, and Package of R8C/2B Group.

Table 1.5 Product List for R8C/2A Group

Current of Nov. 2007

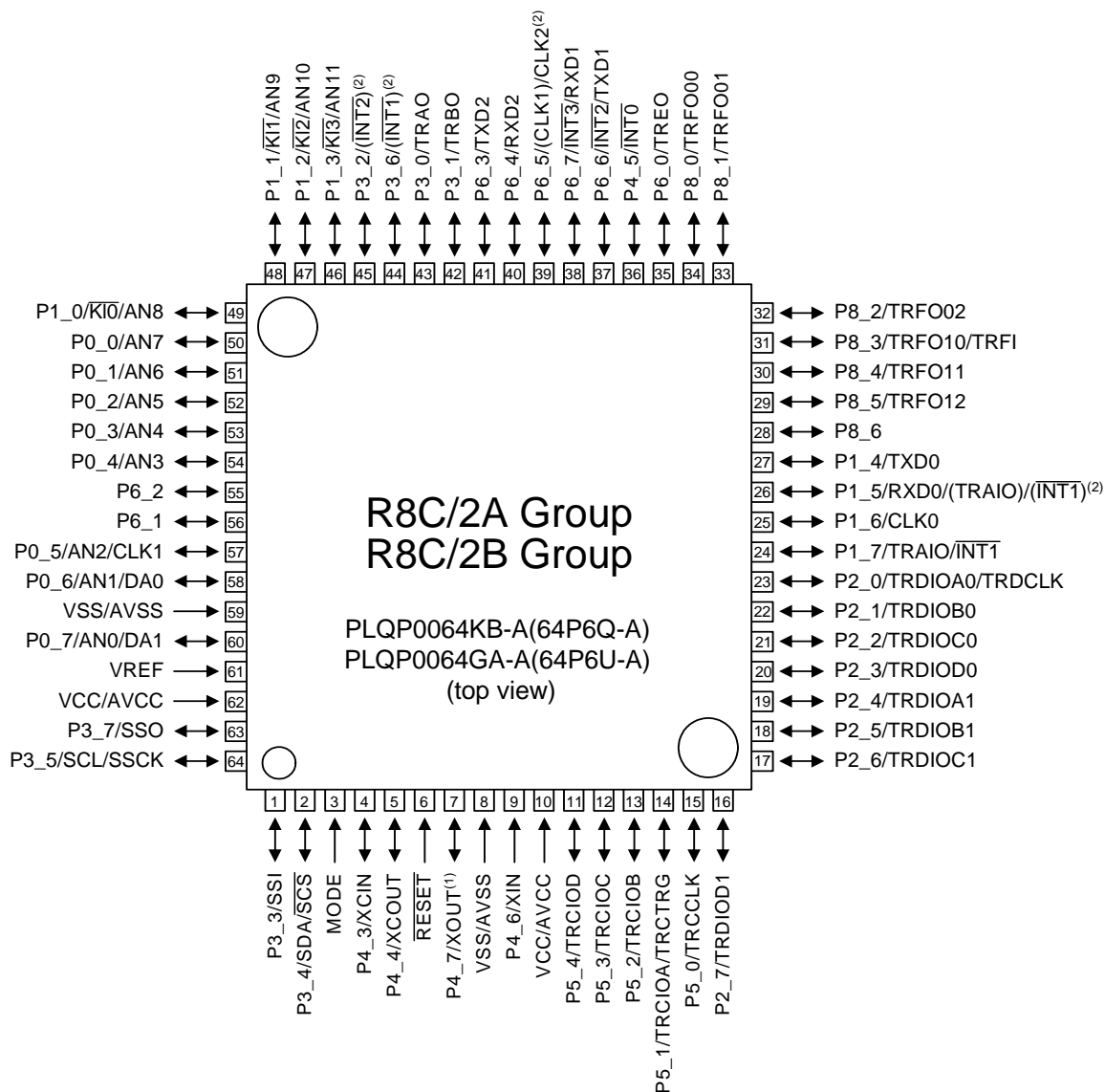
Part No.	ROM Capacity	RAM Capacity	Package Type	Remarks		
R5F212A7SNFP	48 Kbytes	2.5 Kbytes	PLQP0064KB-A	N version		
R5F212A7SNFA	48 Kbytes	2.5 Kbytes	PLQP0064GA-A			
R5F212A7SNLG	48 Kbytes	2.5 Kbytes	PTLG0064JA-A			
R5F212A8SNFP	64 Kbytes	3 Kbytes	PLQP0064KB-A			
R5F212A8SNFA	64 Kbytes	3 Kbytes	PLQP0064GA-A			
R5F212A8SNLG	64 Kbytes	3 Kbytes	PLTG0064JA-A			
R5F212AASNFP	96 Kbytes	7 Kbytes	PLQP0064KB-A			
R5F212AASNFA	96 Kbytes	7 Kbytes	PLQP0064GA-A			
R5F212AASNLG	96 Kbytes	7 Kbytes	PLTG0064JA-A			
R5F212ACSNFP	128 Kbytes	7.5 Kbytes	PLQP0064KB-A			
R5F212ACSNFA	128 Kbytes	7.5 Kbytes	PLQP0064GA-A			
R5F212ACSNLG	128 Kbytes	7.5 Kbytes	PLTG0064JA-A			
R5F212A7SDFP	48 Kbytes	2.5 Kbytes	PLQP0064KB-A	D version		
R5F212A7SDFA	48 Kbytes	2.5 Kbytes	PLQP0064GA-A			
R5F212A8SDFP	64 Kbytes	3 Kbytes	PLQP0064KB-A			
R5F212A8SDFA	64 Kbytes	3 Kbytes	PLQP0064GA-A			
R5F212AASDFP	96 Kbytes	7 Kbytes	PLQP0064KB-A			
R5F212AASDFA	96 Kbytes	7 Kbytes	PLQP0064GA-A			
R5F212ACSDFP	128 Kbytes	7.5 Kbytes	PLQP0064KB-A			
R5F212ACSDFA	128 Kbytes	7.5 Kbytes	PLQP0064GA-A			
R5F212A7SNXXXFP	48 Kbytes	2.5 Kbytes	PLQP0064KB-A	N version	Factory programming product ⁽¹⁾	
R5F212A7SNXXXFA	48 Kbytes	2.5 Kbytes	PLQP0064GA-A			
R5F212A7SNXXXLG	48 Kbytes	2.5 Kbytes	PTLG0064JA-A			
R5F212A8SNXXXFP	64 Kbytes	3 Kbytes	PLQP0064KB-A			
R5F212A8SNXXXFA	64 Kbytes	3 Kbytes	PLQP0064GA-A			
R5F212A8SNXXXLG	64 Kbytes	3 Kbytes	PLTG0064JA-A			
R5F212AASNXXXFP	96 Kbytes	7 Kbytes	PLQP0064KB-A			
R5F212AASNXXXFA	96 Kbytes	7 Kbytes	PLQP0064GA-A			
R5F212AASNXXXLG	96 Kbytes	7 Kbytes	PLTG0064JA-A			
R5F212ACSNXXXFP	128 Kbytes	7.5 Kbytes	PLQP0064KB-A			
R5F212ACSNXXXFA	128 Kbytes	7.5 Kbytes	PLQP0064GA-A			
R5F212ACSNXXXLG	128 Kbytes	7.5 Kbytes	PLTG0064JA-A			
R5F212A7SDXXXFP	48 Kbytes	2.5 Kbytes	PLQP0064KB-A	D version		
R5F212A7SDXXXFA	48 Kbytes	2.5 Kbytes	PLQP0064GA-A			
R5F212A8SDXXXFP	64 Kbytes	3 Kbytes	PLQP0064KB-A			
R5F212A8SDXXXFA	64 Kbytes	3 Kbytes	PLQP0064GA-A			
R5F212AASDXXXFP	96 Kbytes	7 Kbytes	PLQP0064KB-A			
R5F212AASDXXXFA	96 Kbytes	7 Kbytes	PLQP0064GA-A			
R5F212ACSDXXXFP	128 Kbytes	7.5 Kbytes	PLQP0064KB-A			
R5F212ACSDXXXFA	128 Kbytes	7.5 Kbytes	PLQP0064GA-A			

NOTE:

1. The user ROM is programmed before shipment.

1.4 Pin Assignment

Figure 1.4 shows 64-pin LQFP Package Pin Assignment (Top View). Figure 1.5 shows 64-pin FLGA Package Pin Assignment (Top Perspective View). Tables 1.7 and 1.8 outlines the Pin Name Information by Pin Number.



NOTES:

1. P4_7/XOUT are an input-only port.
2. Can be assigned to the pin in parentheses by a program.
3. Confirm the pin 1 position on the package by referring to the package dimensions.

Figure 1.4 64-pin LQFP Package Pin Assignment (Top View)

Table 1.7 Pin Name Information by Pin Number (1)

Pin Number	Control Pin	Port	I/O Pin Functions for of Peripheral Modules					
			Interrupt	Timer	Serial Interface	SSU	I ² C bus	A/D Converter, D/A Converter
1		P3_3				SSI		
2		P3_4				SCS	SDA	
3	MODE							
4	XCIN	P4_3						
5	XCOUT	P4_4						
6	RESET							
7	XOUT	P4_7						
8	VSS/AVSS							
9	XIN	P4_6						
10	VCC/AVCC							
11		P5_4		TRCIOD				
12		P5_3		TRCIOC				
13		P5_2		TRCIOB				
14		P5_1		TRCIOA/TRCTRIG				
15		P5_0		TRCCLK				
16		P2_7		TRDIOD1				
17		P2_6		TRDIOC1				
18		P2_5		TRDIOB1				
19		P2_4		TRDIOA1				
20		P2_3		TRDIOD0				
21		P2_2		TRDIOC0				
22		P2_1		TRDIOB0				
23		P2_0		TRDIOA0/TRDCLK				
24		P1_7	INT1	TRAIO				
25		P1_6			CLK0			
26		P1_5	(INT1) ⁽¹⁾	(TRAIO) ⁽¹⁾	RXD0			
27		P1_4			TXD0			
28		P8_6						
29		P8_5		TRFO12				
30		P8_4		TRFO11				
31		P8_3		TRFO10/TRFI				
32		P8_2		TRFO02				
33		P8_1		TRFO01				
34		P8_0		TRFO00				
35		P6_0		TREO				
36		P4_5	INT0	INT0				
37		P6_6	INT2		TXD1			
38		P6_7	INT3		RXD1			
39		P6_5			(CLK1) ⁽¹⁾ / CLK2			
40		P6_4			RXD2			
41		P6_3			TXD2			
42		P3_1		TRBO				
43		P3_0		TRA0				
44		P3_6	(INT1) ⁽¹⁾					
45		P3_2	(INT2) ⁽¹⁾					

NOTE:

1. Can be assigned to the pin in parentheses by a program.

2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts.

Interrupt are disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1.

The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has higher priority than IPL, the interrupt is enabled.

2.8.10 Reserved Bit

If necessary, set to 0. When read, the content is undefined.

3. Memory

3.1 R8C/2A Group

Figure 3.1 is a Memory Map of R8C/2A Group. The R8C/2A group has 1 Mbyte of address space from addresses 00000h to FFFFFh.

The internal ROM is allocated lower addresses, beginning with address 0FFFFh. For example, a 48-Kbyte internal ROM area is allocated addresses 04000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.

The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 2.5-Kbyte internal RAM area is allocated addresses 00400h to 00DFFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated here. All addresses within the SFR, which have nothing allocated are reserved for future use and cannot be accessed by users.

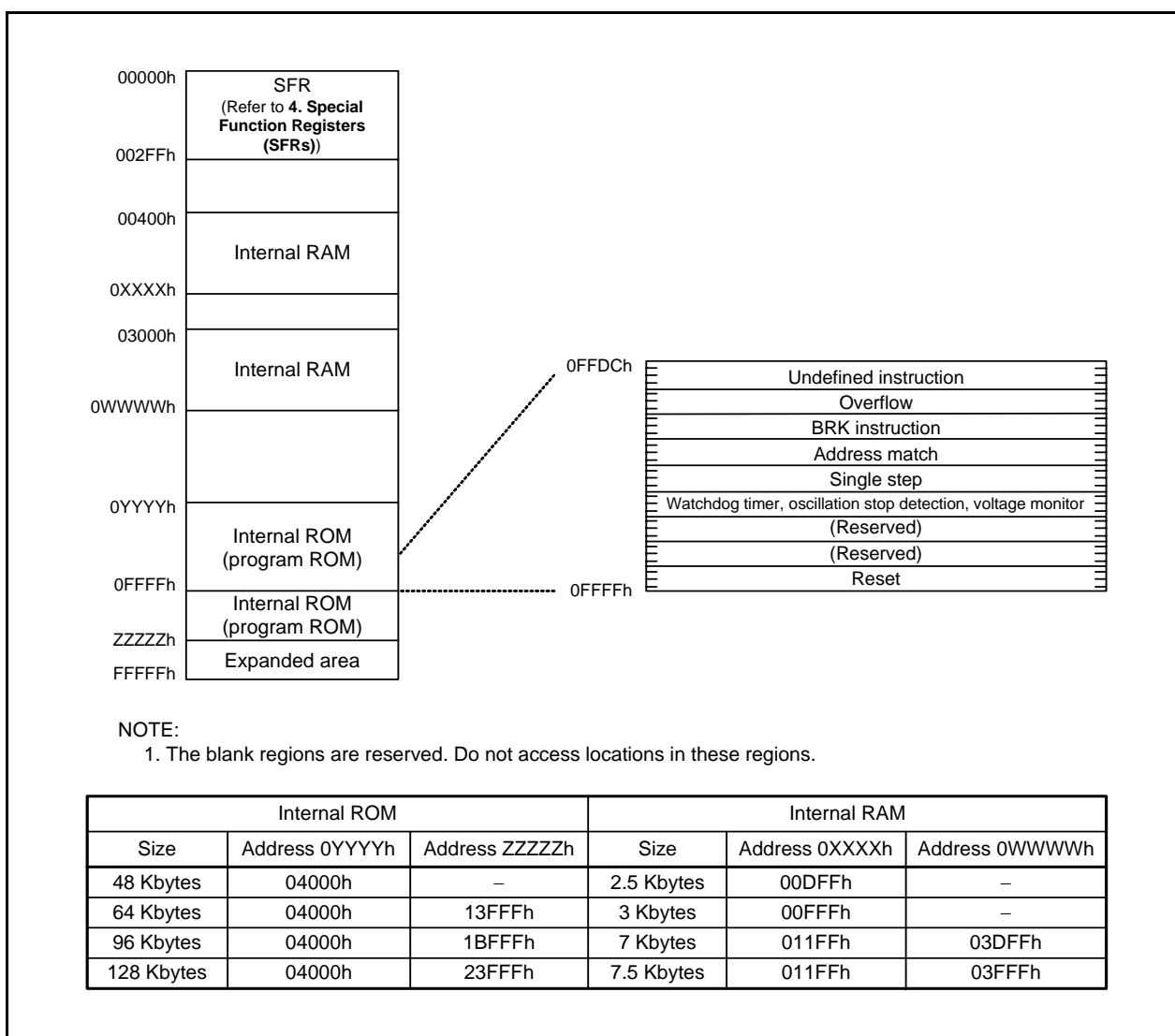


Figure 3.1 Memory Map of R8C/2A Group

4. Special Function Registers (SFRs)

An SFR (special function register) is a control register for a peripheral function. Tables 4.1 to 4.12 list the special function registers.

Table 4.1 SFR Information (1)(1)

Address	Register	Symbol	After reset
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	00h
0005h	Processor Mode Register 1	PM1	00h
0006h	System Clock Control Register 0	CM0	01101000b
0007h	System Clock Control Register 1	CM1	00100000b
0008h	Module Operation Enable Register	MSTCR	00h
0009h			
000Ah	Protect Register	PRCR	00h
000Bh			
000Ch	Oscillation Stop Detection Register	OCD	00000100b
000Dh	Watchdog Timer Reset Register	WDTR	XXh
000Eh	Watchdog Timer Start Register	WDTS	XXh
000Fh	Watchdog Timer Control Register	WDC	00X11111b
0010h	Address Match Interrupt Register 0	RMAD0	00h
0011h			00h
0012h			00h
0013h	Address Match Interrupt Enable Register	AIER	00h
0014h	Address Match Interrupt Register 1	RMAD1	00h
0015h			00h
0016h			00h
0017h			
0018h			
0019h			
001Ah			
001Bh			
001Ch	Count Source Protection Mode Register	CSPR	00h 10000000b ⁽⁶⁾
001Dh			
001Eh			
001Fh			
0020h			
0021h			
0022h			
0023h	High-Speed On-Chip Oscillator Control Register 0	FRA0	00h
0024h	High-Speed On-Chip Oscillator Control Register 1	FRA1	When shipping
0025h	High-Speed On-Chip Oscillator Control Register 2	FRA2	00h
0026h			
0027h			
0028h	Clock Prescaler Reset Flag	CPSRF	00h
0029h			
002Ah			
002Bh	High-Speed On-Chip Oscillator Control Register 6	FRA6	When Shipping
002Ch	High-Speed On-Chip Oscillator Control Register 7	FRA7	When Shipping
0030h			
0031h	Voltage Detection Register 1 ⁽²⁾	VCA1	00001000b
0032h	Voltage Detection Register 2 ⁽²⁾	VCA2	00h ⁽³⁾ 00100000b ⁽⁴⁾
0033h			
0034h			
0035h			
0036h	Voltage Monitor 1 Circuit Control Register ⁽⁵⁾	VW1C	00001000b
0037h	Voltage Monitor 2 Circuit Control Register ⁽⁵⁾	VW2C	00h
0038h	Voltage Monitor 0 Circuit Control Register ⁽²⁾	VW0C	0000X000b ⁽³⁾ 0100X001b ⁽⁴⁾
0039h			
003Ah			
003Eh			
003Fh			

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. Software reset, watchdog timer reset, voltage monitor 1 reset, or voltage monitor 2 reset do not affect this register.
3. The LVD0ON bit in the OFS register is set to 1 and hardware reset.
4. Power-on reset, voltage monitor 0 reset, or the LVD0ON bit in the OFS register is set to 0 and hardware reset.
5. Software reset, watchdog timer reset, voltage monitor 1 reset, or voltage monitor 2 reset do not affect b2 and b3.
6. The CSPROINI bit in the OFS register is set to 0.

Table 4.3 SFR Information (3)⁽¹⁾

Address	Register	Symbol	After reset
0080h			
0081h			
0082h			
0083h			
0084h			
0085h			
0086h			
0087h			
0088h			
0089h			
008Ah			
008Bh			
008Ch			
008Dh			
008Eh			
008Fh			
0090h			
0091h			
0092h			
0093h			
0094h			
0095h			
0096h			
0097h			
0098h			
0099h			
009Ah			
009Bh			
009Ch			
009Dh			
009Eh			
009Fh			
00A0h	UART0 Transmit/Receive Mode Register	U0MR	00h
00A1h	UART0 Bit Rate Register	U0BRG	XXh
00A2h	UART0 Transmit Buffer Register	U0TB	XXh
00A3h			XXh
00A4h	UART0 Transmit/Receive Control Register 0	U0C0	00001000b
00A5h	UART0 Transmit/Receive Control Register 1	U0C1	00000010b
00A6h	UART0 Receive Buffer Register	U0RB	XXh
00A7h			XXh
00A8h	UART1 Transmit/Receive Mode Register	U1MR	00h
00A9h	UART1 Bit Rate Register	U1BRG	XXh
00AAh	UART1 Transmit Buffer Register	U1TB	XXh
00ABh			XXh
00ACh	UART1 Transmit/Receive Control Register 0	U1C0	00001000b
00ADh	UART1 Transmit/Receive Control Register 1	U1C1	00000010b
00AEh	UART1 Receive Buffer Register	U1RB	XXh
00AFh			XXh
00B0h			
00B1h			
00B2h			
00B3h			
00B4h			
00B5h			
00B6h			
00B7h			
00B8h	SS Control Register H / IIC bus Control Register 1 ⁽²⁾	SSCRH / ICCR1	00h
00B9h	SS Control Register L / IIC bus Control Register 2 ⁽²⁾	SSCRL / ICCR2	01111101b
00BAh	SS Mode Register / IIC bus Mode Register ⁽²⁾	SSMR / ICMR	00011000b
00BBh	SS Enable Register / IIC bus Interrupt Enable Register ⁽²⁾	SSER / ICIER	00h
00BCh	SS Status Register / IIC bus Status Register ⁽²⁾	SSSR / ICSR	00h / 0000X000b
00BDh	SS Mode Register 2 / Slave Address Register ⁽²⁾	SSMR2 / SAR	00h
00BEh	SS Transmit Data Register / IIC bus Transmit Data Register ⁽²⁾	SSTDR / ICDRT	FFh
00BFh	SS Receive Data Register / IIC bus Receive Data Register ⁽²⁾	SSRDR / ICDRR	FFh

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. Selected by the IICSEL bit in the PMR register.

Table 4.7 SFR Information (7)(1)

Address	Register	Symbol	After reset
0180h			
0181h			
0182h			
0183h			
0184h			
0185h			
0186h			
0187h			
0188h			
0189h			
018Ah			
018Bh			
018Ch			
018Dh			
018Eh			
018Fh			
0190h			
0191h			
0192h			
0193h			
0194h			
0195h			
0196h			
0197h			
0198h			
0199h			
019Ah			
019Bh			
019Ch			
019Dh			
019Eh			
019Fh			
01A0h			
01A1h			
01A2h			
01A3h			
01A4h			
01A5h			
01A6h			
01A7h			
01A8h			
01A9h			
01AAh			
01ABh			
01ACh			
01ADh			
01AEh			
01AFh			
01B0h			
01B1h			
01B2h			
01B3h	Flash Memory Control Register 4	FMR4	01000000b
01B4h			
01B5h	Flash Memory Control Register 1	FMR1	1000000Xb
01B6h			
01B7h	Flash Memory Control Register 0	FMR0	00000001b
01B8h			
01B9h			
01BAh			
01BBh			
01BCh			
01BDh			
01BEh			
01BFh			

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 4.11 SFR Information (11)(1)

Address	Register	Symbol	After reset
0280h			
0281h			
0282h			
0283h			
0284h			
0285h			
0286h			
0287h			
0288h			
0289h			
028Ah			
028Bh			
028Ch			
028Dh			
028Eh			
028Fh			
0290h	Timer RF Register	TRF	00h
0291h			00h
0292h			
0293h			
0294h			
0295h			
0296h			
0297h			
0298h			
0299h			
029Ah	Timer RF Control Register 0	TRFCR0	00h
029Bh	Timer RF Control Register 1	TRFCR1	00h
029Ch	Capture / Compare 0 Register	TRFM0	0000h ⁽²⁾
029Dh			FFFFh ⁽³⁾
029Eh	Compare 1 Register	TRFM1	FFh
029Fh			FFh
02A0h			
02A1h			
02A2h			
02A3h			
02A4h			
02A5h			
02A6h			
02A7h			
02A8h			
02A9h			
02AAh			
02ABh			
02ACh			
02ADh			
02AEh			
02AFh			
02B0h			
02B1h			
02B2h			
02B3h			
02B4h			
02B5h			
02B6h			
02B7h			
02B8h			
02B9h			
02BAh			
02BBh			
02BCh			
02BDh			
02BEh			
02BFh			

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. After input capture mode.
3. After output compare mode.

Table 4.12 SFR Information (12)(1)

Address	Register	Symbol	After reset
02C0h	A/D Register 0	AD0	XXh
02C1h			XXh
02C2h			
02C3h			
02C4h			
02C5h			
02C6h			
02C7h			
02C8h			
02C9h			
02CAh			
02CBh			
02CCh			
02CDh			
02CEh			
02CFh			
02D0h			
02D1h			
02D2h	A/D Control Register 2	ADCON2	00001000b
02D3h			
02D4h	A/D Control Register 0	ADCON0	00000011b
02D5h			
02D6h	A/D Control Register 1	ADCON1	00h
02D7h			
02D8h			
02D9h			
02DAh			
02DBh			
02DCh			
02DDh			
02DEh			
02DFh			
02E0h			
02E1h			
02E2h			
02E3h			
02E4h	Port P8 Direction Register	PD8	00h
02E5h	Port P8 Register	P8	XXh
02E6h			
02E7h			
02E8h			
02E9h			
02EAh			
02EBh			
02ECh			
02EDh			
02EEh			
02EFh			
02F0h			
02F1h			
02F2h			
02F3h			
02F4h			
02F5h			
02F6h			
02F7h			
02F8h			
02F9h			
02FAh			
02FBh			
02FCh	Pull-Up Control Register 2	PUR2	XXX00000b
02FDh			
02FEh			
02FFh	Timer RF Output Control Register	TRFOUT	00h
FFFFh	Option Function Select Register	OFS	(Note 2)

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. The OFS register cannot be changed by a program. Use a flash programmer to write to it.

5. Electrical Characteristics

The electrical characteristics of N version ($T_{opr} = -20^{\circ}\text{C}$ to 85°C) and D version ($T_{opr} = -40^{\circ}\text{C}$ to 85°C) are listed below.

Please contact Renesas Technology sales offices for the electrical characteristics in the Y version ($T_{opr} = -20^{\circ}\text{C}$ to 105°C).

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated Value	Unit
V_{CC}/AV_{CC}	Supply voltage		-0.3 to 6.5	V
V_I	Input voltage		-0.3 to $V_{CC} + 0.3$	V
V_O	Output voltage		-0.3 to $V_{CC} + 0.3$	V
P_d	Power dissipation	$T_{opr} = 25^{\circ}\text{C}$	700	mW
T_{opr}	Operating ambient temperature		-20 to 85 (N version) / -40 to 85 (D version)	$^{\circ}\text{C}$
T_{stg}	Storage temperature		-65 to 150	$^{\circ}\text{C}$

Table 5.5 Flash Memory (Program ROM) Electrical Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
–	Program/erase endurance ⁽²⁾	R8C/2A Group	100 ⁽³⁾	–	–	times
		R8C/2B Group	1,000 ⁽³⁾	–	–	times
–	Byte program time		–	50	400	μs
–	Block erase time		–	0.4	9	s
t _d (SR-SUS)	Time delay from suspend request until suspend		–	–	97+CPU clock × 6 cycles	μs
–	Interval from erase start/restart until following suspend request		650	–	–	μs
–	Interval from program start/restart until following suspend request		0	–	–	ns
–	Time from suspend until program/erase restart		–	–	3+CPU clock × 4 cycles	μs
–	Program, erase voltage		2.7	–	5.5	V
–	Read voltage		2.2	–	5.5	V
–	Program, erase temperature		0	–	60	°C
–	Data hold time ⁽⁷⁾	Ambient temperature = 55°C	20	–	–	year

NOTES:

1. V_{CC} = 2.7 to 5.5 V at T_{opr} = 0 to 60°C, unless otherwise specified.
2. Definition of programming/erasure endurance
The programming and erasure endurance is defined on a per-block basis.
If the programming and erasure endurance is n (n = 100 or 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
4. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erase count of each block and limit the number of erase operations to a certain number.
5. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
6. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
7. The data hold time includes time that the power supply is off or the clock is not supplied.

Table 5.6 Flash Memory (Data flash Block A, Block B) Electrical Characteristics⁽⁴⁾

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance ⁽²⁾		10,000 ⁽³⁾	—	—	times
—	Byte program time (program/erase endurance ≤ 1,000 times)		—	50	400	μs
—	Byte program time (program/erase endurance > 1,000 times)		—	65	—	μs
—	Block erase time (program/erase endurance ≤ 1,000 times)		—	0.2	9	s
—	Block erase time (program/erase endurance > 1,000 times)		—	0.3	—	s
t _d (SR-SUS)	Time delay from suspend request until suspend		—	—	97+CPU clock × 6 cycles	μs
—	Interval from erase start/restart until following suspend request		650	—	—	μs
—	Interval from program start/restart until following suspend request		0	—	—	ns
—	Time from suspend until program/erase restart		—	—	3+CPU clock × 4 cycles	μs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		2.2	—	5.5	V
—	Program, erase temperature		-20 ⁽⁸⁾	—	85	°C
—	Data hold time ⁽⁹⁾	Ambient temperature = 55 °C	20	—	—	year

NOTES:

1. V_{CC} = 2.7 to 5.5 V at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
2. Definition of programming/erasure endurance
The programming and erasure endurance is defined on a per-block basis.
If the programming and erasure endurance is n (n = 100 or 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
4. Standard of block A and block B when program and erase endurance exceeds 1,000 times. Byte program time to 1,000 times is the same as that in program ROM.
5. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erase count of each block and limit the number of erase operations to a certain number.
6. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
7. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
8. -40°C for D version.
9. The data hold time includes time that the power supply is off or the clock is not supplied.

Table 5.10 Power-on Reset Circuit, Voltage Monitor 0 Reset Electrical Characteristics⁽³⁾

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V _{por1}	Power-on reset valid voltage ⁽⁴⁾		–	–	0.1	V
V _{por2}	Power-on reset or voltage monitor 0 reset valid voltage		0	–	V _{det0}	V
tr _{th}	External power V _{CC} rise gradient ⁽²⁾		20	–	–	mV/msec

NOTES:

1. The measurement condition is T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
2. This condition (external power V_{CC} rise gradient) does not apply if V_{CC} ≥ 1.0 V.
3. To use the power-on reset function, enable voltage monitor 0 reset by setting the LVD0ON bit in the OFS register to 0, the VW0C0 and VW0C6 bits in the VW0C register to 1 respectively, and the VCA25 bit in the VCA2 register to 1.
4. t_{w(por1)} indicates the duration the external power V_{CC} must be held below the effective voltage (V_{por1}) to enable a power on reset. When turning on the power for the first time, maintain t_{w(por1)} for 30 s or more if -20°C ≤ T_{opr} ≤ 85°C, maintain t_{w(por1)} for 3,000 s or more if -40°C ≤ T_{opr} < -20°C.

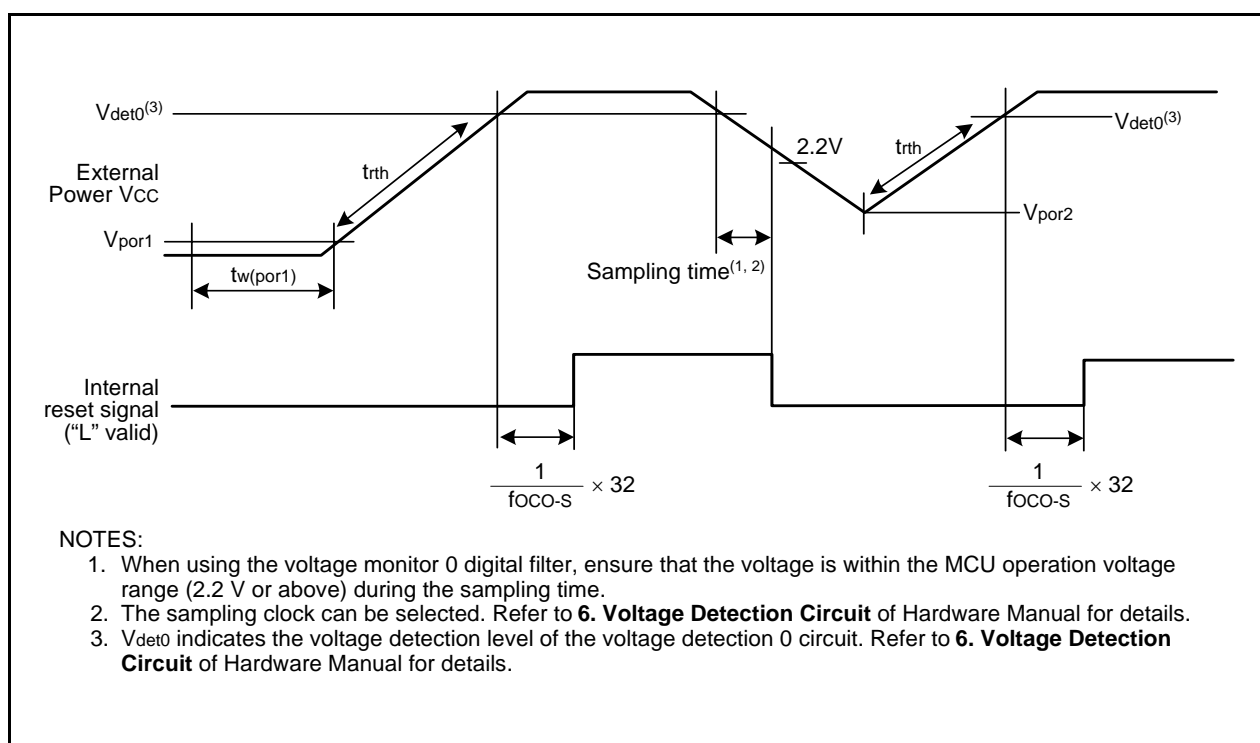
**Figure 5.3 Power-on Reset Circuit Electrical Characteristics**

Table 5.14 Timing Requirements of Clock Synchronous Serial I/O with Chip Select⁽¹⁾

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
tsucyc	SSCK clock cycle time			4	–	–	tcyc ⁽²⁾
tHI	SSCK clock "H" width			0.4	–	0.6	tsucyc
tLO	SSCK clock "L" width			0.4	–	0.6	tsucyc
tRISE	SSCK clock rising time	Master		–	–	1	tcyc ⁽²⁾
		Slave		–	–	1	μs
tFALL	SSCK clock falling time	Master		–	–	1	tcyc ⁽²⁾
		Slave		–	–	1	μs
tsu	SSO, SSI data input setup time			100	–	–	ns
tH	SSO, SSI data input hold time			1	–	–	tcyc ⁽²⁾
tLEAD	\overline{SCS} setup time	Slave		1tcyc + 50	–	–	ns
tLAG	\overline{SCS} hold time	Slave		1tcyc + 50	–	–	ns
tOD	SSO, SSI data output delay time			–	–	1	tcyc ⁽²⁾
tSA	SSI slave access time		2.7 V ≤ Vcc ≤ 5.5 V	–	–	1.5tcyc + 100	ns
			2.2 V ≤ Vcc < 2.7 V	–	–	1.5tcyc + 200	ns
tOR	SSI slave out open time		2.7 V ≤ Vcc ≤ 5.5 V	–	–	1.5tcyc + 100	ns
			2.2 V ≤ Vcc < 2.7 V	–	–	1.5tcyc + 200	ns

NOTES:

1. Vcc = 2.2 to 5.5 V, Vss = 0 V at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
2. 1tcyc = 1/f₁(s)

Table 5.16 Electrical Characteristics (1) [V_{CC} = 5 V]

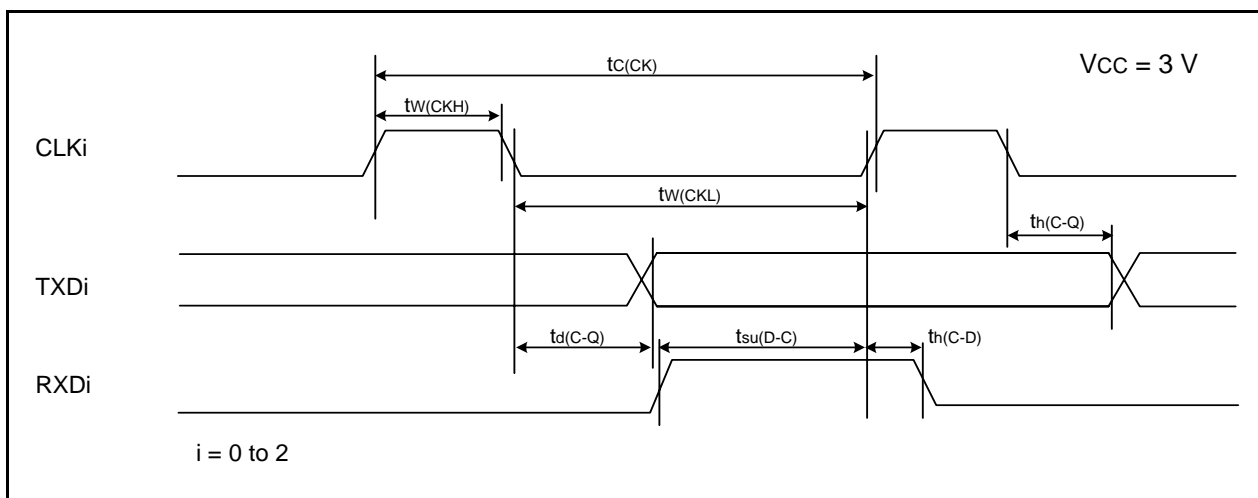
Symbol	Parameter		Condition	Standard			Unit
				Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Except P2_0 to P2_7, XOUT	I _{OH} = -5 mA	V _{CC} - 2.0	—	V _{CC}	V
			I _{OH} = -200 μ A	V _{CC} - 0.5	—	V _{CC}	V
		P2_0 to P2_7	Drive capacity HIGH I _{OH} = -20 mA	V _{CC} - 2.0	—	V _{CC}	V
			Drive capacity LOW I _{OH} = -5 mA	V _{CC} - 2.0	—	V _{CC}	V
		XOUT	Drive capacity HIGH I _{OH} = -1 mA	V _{CC} - 2.0	—	V _{CC}	V
			Drive capacity LOW I _{OH} = -500 μ A	V _{CC} - 2.0	—	V _{CC}	V
V _{OL}	Output "L" voltage	Except P2_0 to P2_7, XOUT	I _{OL} = 5 mA	—	—	2.0	V
			I _{OL} = 200 μ A	—	—	0.45	V
		P2_0 to P2_7	Drive capacity HIGH I _{OL} = 20 mA	—	—	2.0	V
			Drive capacity LOW I _{OL} = 5 mA	—	—	2.0	V
		XOUT	Drive capacity HIGH I _{OL} = 1 mA	—	—	2.0	V
			Drive capacity LOW I _{OL} = 500 μ A	—	—	2.0	V
V _{T+} -V _{T-}	Hysteresis	$\overline{\text{INT0}}, \overline{\text{INT1}}, \overline{\text{INT2}}, \overline{\text{INT3}}, \text{KI0}, \text{KI1}, \text{KI2}, \text{KI3}, \text{TRAIO}, \text{TRFI}, \text{RXD0}, \text{RXD1}, \text{CLK0}, \text{CLK1}, \text{CLK2}, \text{SSI}, \text{SCL}, \text{SDA}, \text{SSO}$		0.1	0.5	—	V
		$\overline{\text{RESET}}$		0.1	1.0	—	V
I _{IH}	Input "H" current		V _I = 5 V	—	—	5.0	μ A
I _{IL}	Input "L" current		V _I = 0 V	—	—	-5.0	μ A
R _{PULLUP}	Pull-up resistance		V _I = 0 V	30	50	167	k Ω
R _{FXIN}	Feedback resistance	XIN		—	1.0	—	M Ω
R _{FXCIN}	Feedback resistance	XCIN		—	18	—	M Ω
V _{RAM}	RAM hold voltage		During stop mode	1.8	—	—	V

NOTE:

- V_{CC} = 4.2 to 5.5 V at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), f(XIN) = 20 MHz, unless otherwise specified.

Table 5.28 Serial Interface

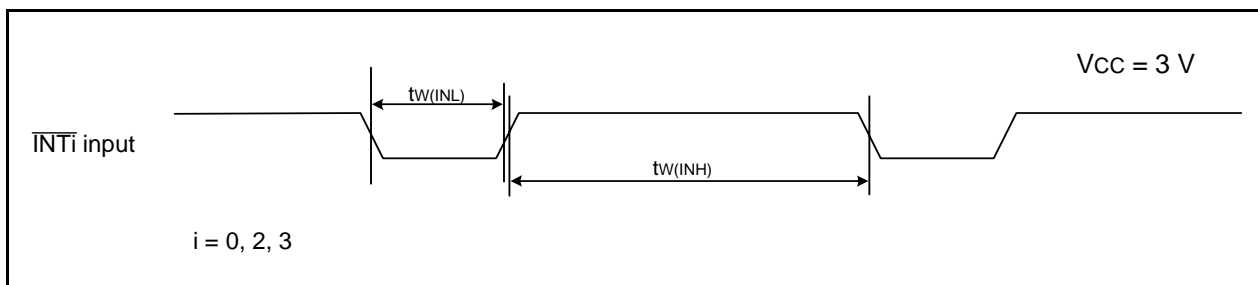
Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	300	—	ns
$t_{w(CKH)}$	CLKi input "H" width	150	—	ns
$t_{w(CKL)}$	CLKi Input "L" width	150	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	80	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	70	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

 $i = 0 \text{ to } 2$ **Figure 5.16 Serial Interface Timing Diagram when Vcc = 3 V****Table 5.29 External Interrupt \overline{INTi} ($i = 0, 2, 3$) Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INT0}$ input "H" width	380 ⁽¹⁾	—	ns
$t_{w(INL)}$	$\overline{INT0}$ input "L" width	380 ⁽²⁾	—	ns

NOTES:

1. When selecting the digital filter by the \overline{INTi} input filter select bit, use an \overline{INTi} input HIGH width of either (1/digital filter clock frequency \times 3) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the \overline{INTi} input filter select bit, use an \overline{INTi} input LOW width of either (1/digital filter clock frequency \times 3) or the minimum value of standard, whichever is greater.

**Figure 5.17 External Interrupt \overline{INTi} Input Timing Diagram when Vcc = 3 V**

**Table 5.31 Electrical Characteristics (6) [V_{CC} = 2.2 V]
(T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.)**

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
I _{CC}	Power supply current (V _{CC} = 2.2 to 2.7 V) Single-chip mode, output pins are open, other pins are V _{SS}	High-speed clock mode	—	2.5	—	mA
		High-speed on-chip oscillator mode	—	1	—	mA
		High-speed on-chip oscillator mode	—	4	—	mA
		Low-speed on- chip oscillator mode	—	1.7	—	mA
		Low-speed on- chip oscillator mode	—	110	300	μA
		Low-speed clock mode	—	125	350	μA
		Low-speed clock mode	—	27	—	μA
		Wait mode	—	20	60	μA
		Wait mode	—	12	40	μA
		Wait mode	—	2.8	—	μA
		Wait mode	—	1.9	—	μA
		Stop mode	—	0.6	3.0	μA
		Stop mode	—	1.60	—	μA

REVISION HISTORY	R8C/2A Group, R8C/2B Group Datasheet
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Rev.	Date	Description	
		Page	Summary
2.00	Oct 17, 2007	33	Table 5.1; Pd: Rated Value "TBD" → "700" revised, "NOTE1" added
		59	Package Dimensions "PTLG0064JA-A (64F0G) package" added
2.10	Nov 26, 2007	2, 4	Table 1.1, Table 1.3 Clock: "Real-time clock (timer RE)" added
		6, 7	Table 1.5 and Figure 1.1 revised
		8, 9	Table 1.6 and Figure 1.2 revised
		20, 21	Figure 3.1 and Figure 3.2 revised
		22	Table 4.1 002Ch: High-Speed On-Chip Oscillator Control Register 7 added
		35	Table 5.2 NOTE2 revised
		41	Table 5.11 revised

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